

20mm BIG LAMP

Part Number: DLC/6ID

High Efficiency Red

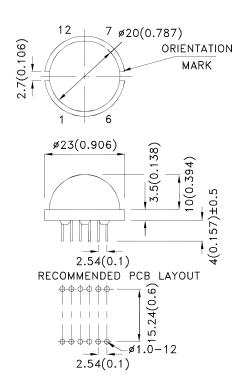
Features

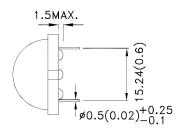
- 12 pins.
- High luminous intensity.
- Low power consumption.
- Wide viewing angle.
- Categorized for luminous intensity.
- Excellent on / off contrast.
- Easy mounting on P.C. board or sockets.
- Solid state reliability.
- RoHS compliant.

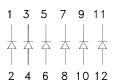
Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions











- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
 The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
		,,	Min.	Тур.	201/2
DLC/6ID	High Efficiency Red (GaAsP/GaP)	Red Diffused	20	49	120°
		Rea Diliasea	*6	*17	

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	617		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	I=20mA
lR	Reverse Current	High Efficiency Red		10	uA	VR = 5V

- 1.Wavelength: +/-1nm.
- Forward Voltage: +/-0.1V.
 Wavelength value is traceable to the CIE127-2007 compliant national standards.

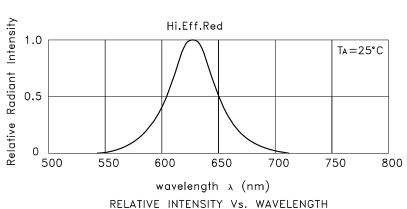
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3-5 Seconds		

- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. 2mm below package base.

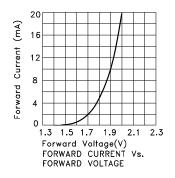
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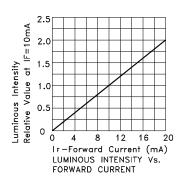
Luminous intensity/ luminous Flux: +/-15%.
 *Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

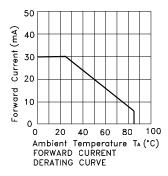


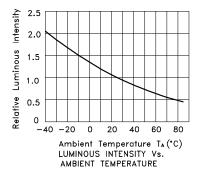
RELATIVE INTENSITY VS. WAVELENGTH

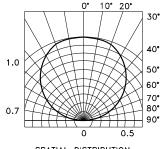
High Efficiency Red DLC/6ID







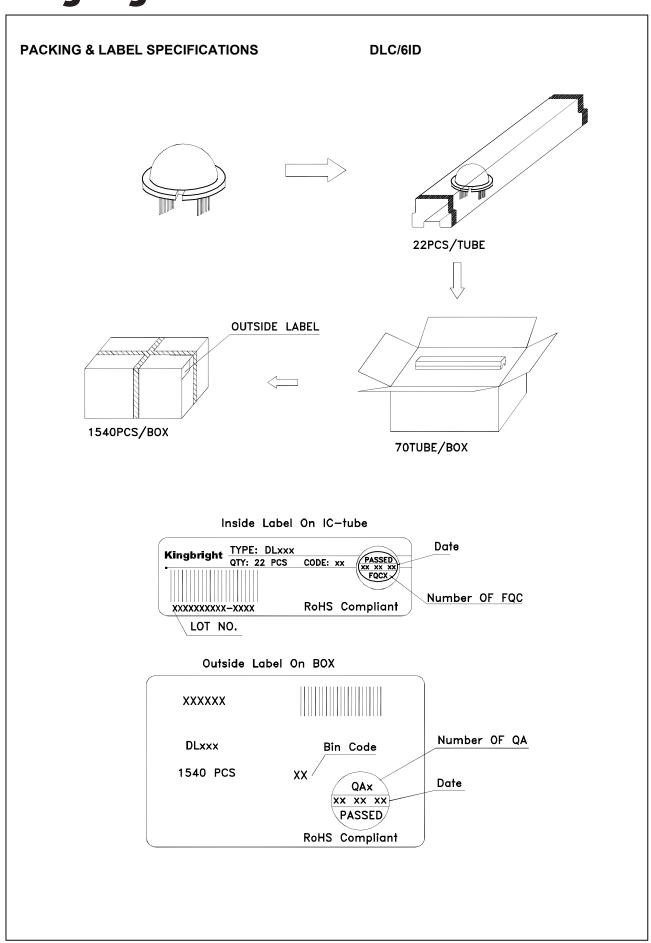




SPATIAL DISTRIBUTION

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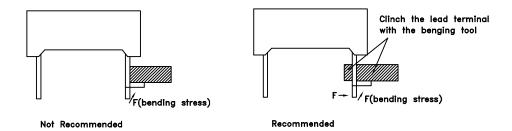
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THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Do not bend the component leads by hand without proper tools. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

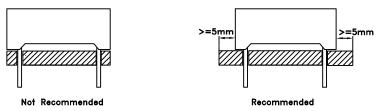


Installation

- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.

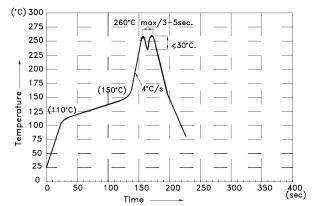


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DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering , the PCB top—surface temperature should be kept below 105°C 5.No more than once.

Soldering General Notes:

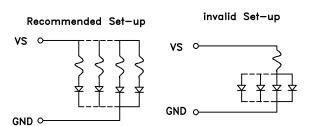
- 1. Through—hole displays are incompatible with reflow soldering.
- 2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- 2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

- 1.Protective current—limiting resistors may be necessary to operate the Displays.
- 2.LEDs mounted in parallel should each be placed in series with its own current—limiting resistor.



Detailed application notes are listed on our website. http://www.kingbright.com/application notes

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